

Description

Features

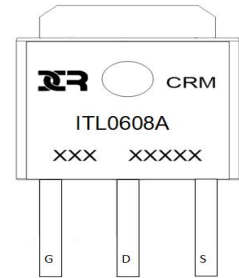
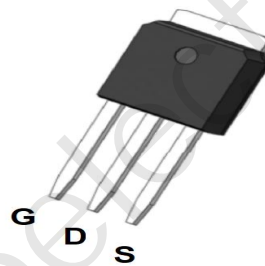
- 60V, 80A
 $R_{DS(ON)}$ Typ = 5.2mΩ @ $V_{GS} = 10V$
 $R_{DS(ON)}$ Typ = 5.9mΩ @ $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	TUBE (pcs)	Inner Box (pcs)	Per Carton (pcs)
CRMITL0608A	CRMITL0608A	TO-251-3L	TUBE	72	4320	21600

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	60	V
V_{GS}	Gate-to-Source Voltage	±20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	80 A
		$T_C = 100^\circ\text{C}$	48 A
I_{DM}	Pulsed Drain Current ⁽¹⁾	320	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	156	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	114 W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.1	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.6	2.2	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 20A	-	5.2	6.8	mΩ
		V _{GS} = 4.5V, I _D = 10A	-	5.9	7.7	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	-	4765	-	pF
C _{oss}	Output Capacitance		-	277	-	pF
C _{rss}	Reverse Transfer Capacitance		-	245	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 30V, I _D = 10A	-	98.0	-	nC
Q _{gs}	Gate Source Charge		-	12.5	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	32	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 30V I _D = 15A, R _{GEN} = 1.8Ω	-	9	-	ns
t _r	Turn-On Rise Time		-	6.1	-	ns
t _{d(off)}	Turn-Off DelayTime		-	33.2	-	ns
t _f	Turn-Off Fall Time		-	7.5	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current	V _{GS} = 0V, I _S = 30A	-	-	80	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	320	A
V _{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	31	-	ns
Qrr	Body Diode Reverse Recovery Charge		I _F = 15A, di/dt = 100A/us	-	48	-

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 30\text{V}$, $V_G = 10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$, $I_{AS} = 25\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

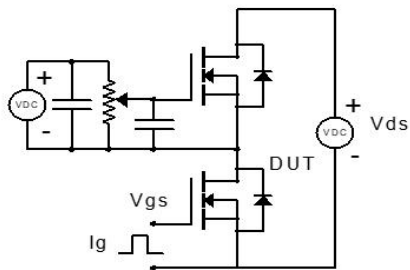


Figure 1: Gate Charge Test Circuit & Waveform

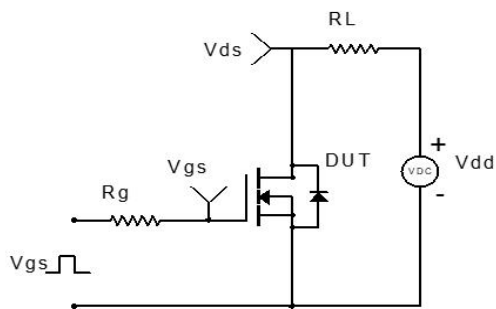


Figure 2: Resistive Switching Test Circuit & Waveform

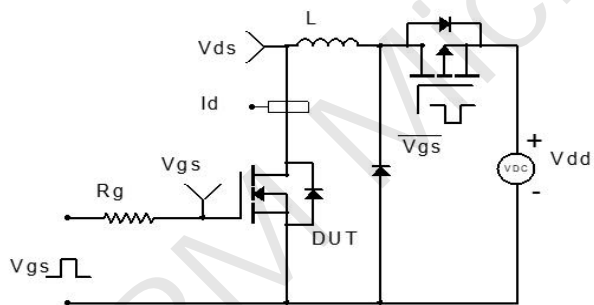
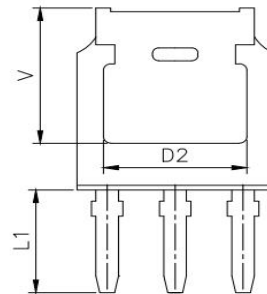
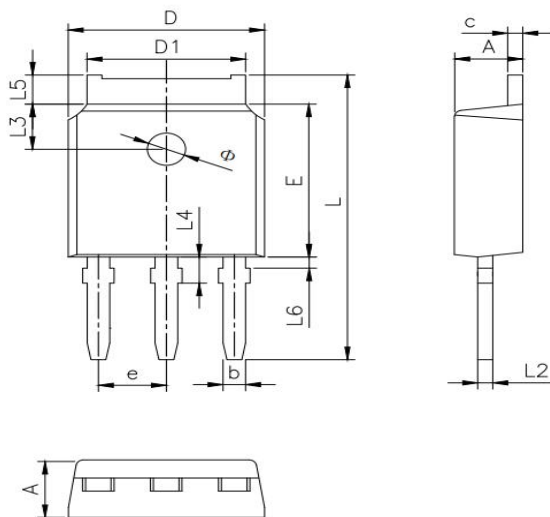


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-251-3L)




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
b	0.66	0.76	0.86
c	0.46	0.51	0.58
D	6.50	6.60	6.70
D1	5.10	5.33	5.46
D2	4.83 REF.		
E	6.00	6.10	6.20
e	2.19	2.29	2.39
L	11.02	11.22	11.42
L1	4.10 REF.		
L2	0.508BSC		
L3	1.80 REF.		
L4	0.95	1.05	1.15
L5	0.90	—	1.25
L6	0.15	—	0.75
Φ	1.10	—	1.30
V	5.40 REF.		

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